

Noctua Intros NT-H2 Thermal Compound

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Cooling specialist Noctua announces a 2nd generation thermal compound-- NT-H2, an "enthusiast-grade" paste consisting of a mixture of fine-tuned metal oxide and microparticles for lower thermal resistance and reduced bond-line thickness.



NT-H2 is a successor to NT-H1, a thermal compound Noctua released back in 2007. The updated compound promises even better performance in most application scenarios, since it shows up to 2° C lower temperatures in standardised internal tests at various platforms and heat loads. Excellent long-term stability means it does need a break-in period, and it can be used on the CPU for up to 5 years.

The paste is electrically non-conductive and non-corroding, meaning no risk of short circuits, and is safe to use with all types of heatsinks. It is available in standard 3.5g and extra-large 10g packages including three (3.5g) and ten (10g) NA-CW1 cleaning wipes. Pre-moistened in a custom detergent mixture, the wipes are ideal for cleaning CPUs, GPUs and heatsink contact surfaces.

Noctua offers NA-CW1 wipes separately in sets of 20 (NA-SCW1). Also available is a 10g package of NT-H1 ideal for power users or for large processors demanding larger volumes of thermal compound.

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